

Matt Tin-Lead LA

The Matt Tin-Lead LA is mainly applied for plating of printed circuit boards, but also for plating of other electronic components. The borofluoric acid based electrolyte deposits fine crystalline coatings. The tin content in the deposited coating is approx. 60 %, which can be varied depending on the chosen electrolyte composition. The electrolyte can be made-up in two variants. The common make-up allows current densities of 1 -3 A/dm². With reduced metal concentration current densities up to 1.5 A/dm² are possible. This variant has the advantage of less drag-out losses.

The Matt Tin-Lead LA is very economical. The organic additives are almost only consumed by electrolyte drag-out. All additives may be determined by analysis. Even after prolonged storage periods the coatings have excellent reflow characteristics and solderability, in oil as well as in infrared operated plants.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given. We reserve the right to make technical changes as necessary. In the interests of safety, please pay attention to the R- and S- phrases on the labels of the containers. The minimum shelf life of the additives is printed on the label of the container. The current IMDS number of the layer deposited from the process can be found on the internet at www.schloetter.com/downloads.

For the storage of chemical products only the TRGS 514 and TRGS 515 regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) is only valid **for transportation** and must not be applied to storage.

